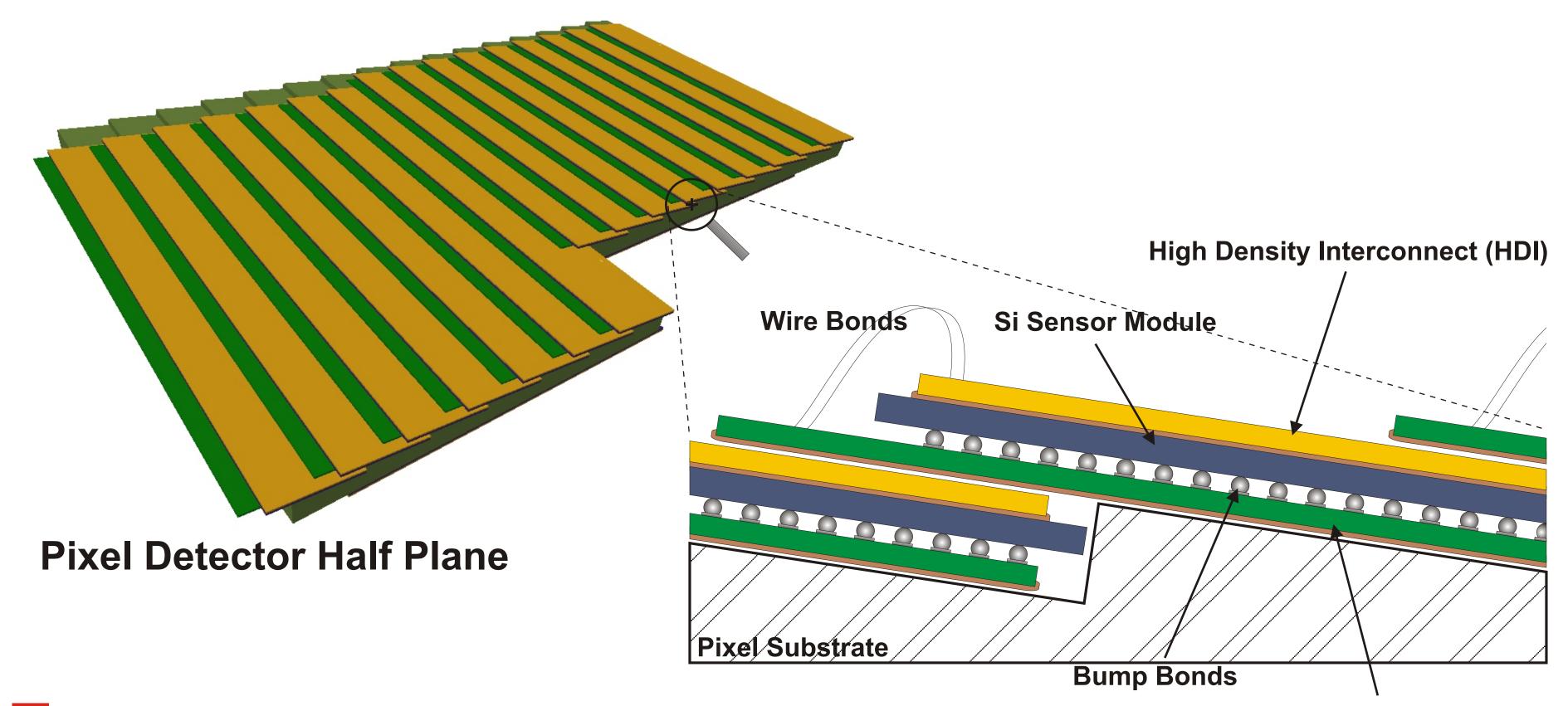
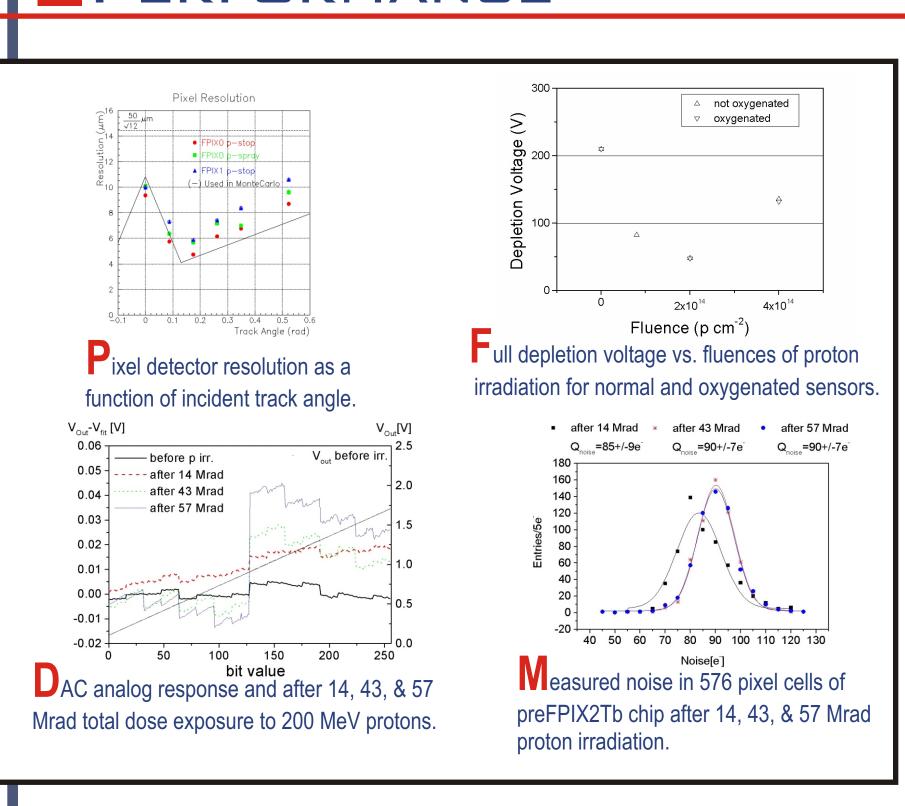
BTeV Pixel Detector R&D



PERFORMANCE

FPIX2 Read Out Chips



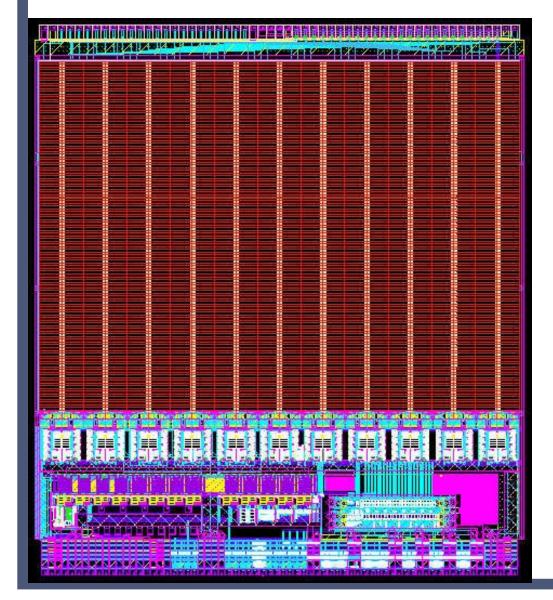
Multichip sensor bump-bonded to 5 FPIX1 read-out chips.

Multichip module with 1 read-out chip bump-bonded to single sensor and wire-bonded to HDI

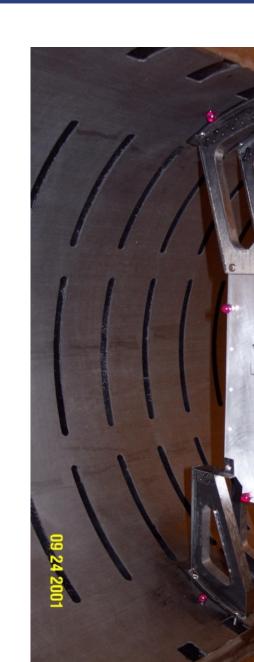


wire-bonded to HDI undergoing characterization tests.

FPIX2 READOUT



Layout of the new FPIX2 pixel read-out chip for BTeV to be submitted soon using a 0.25 micron CMOS process observing radiation tolerant design rules.



Carbon fiber cylindrical support shell and mounting brackets for the pixel substrates (Al dummy version shown here) undergoing mechanical stress tests.

